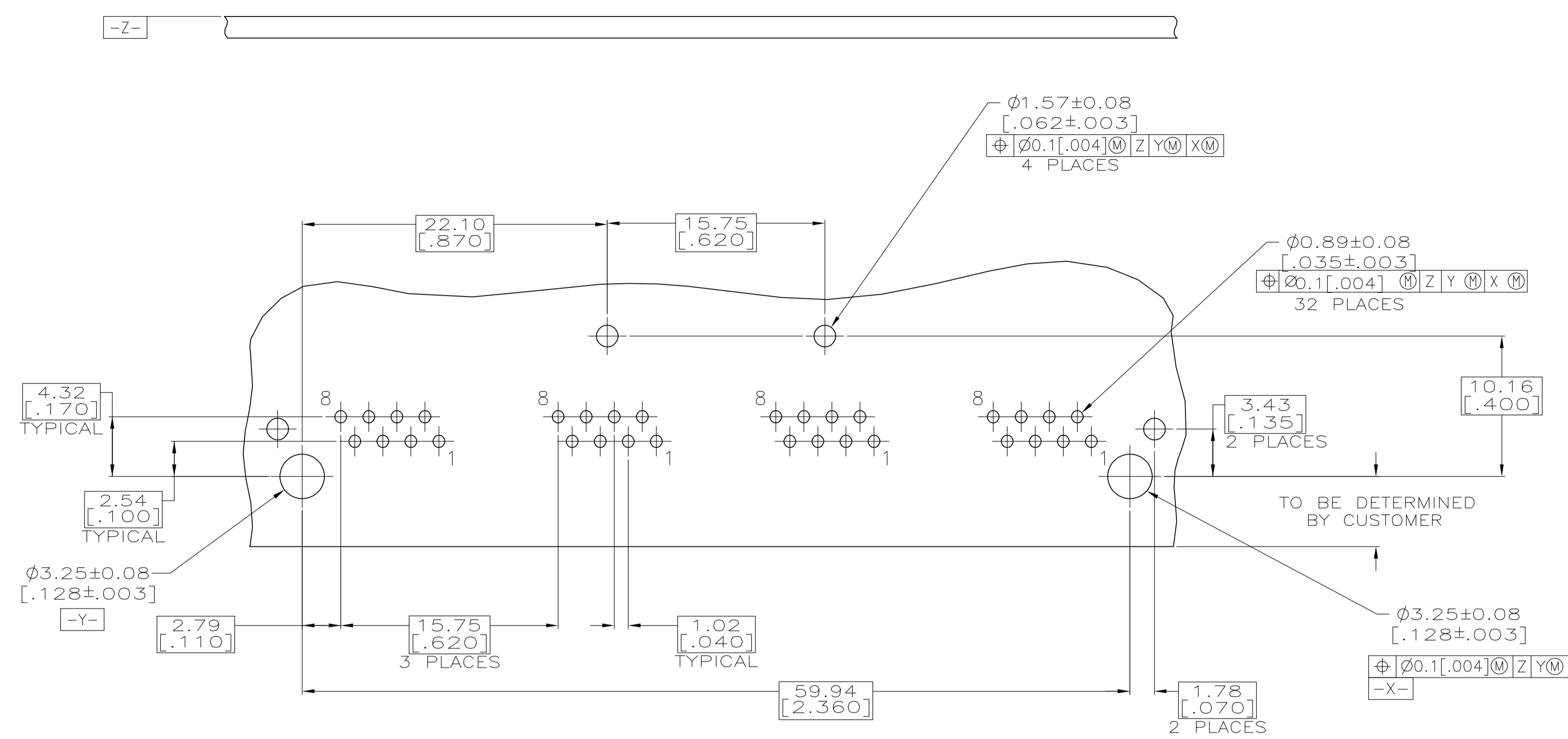
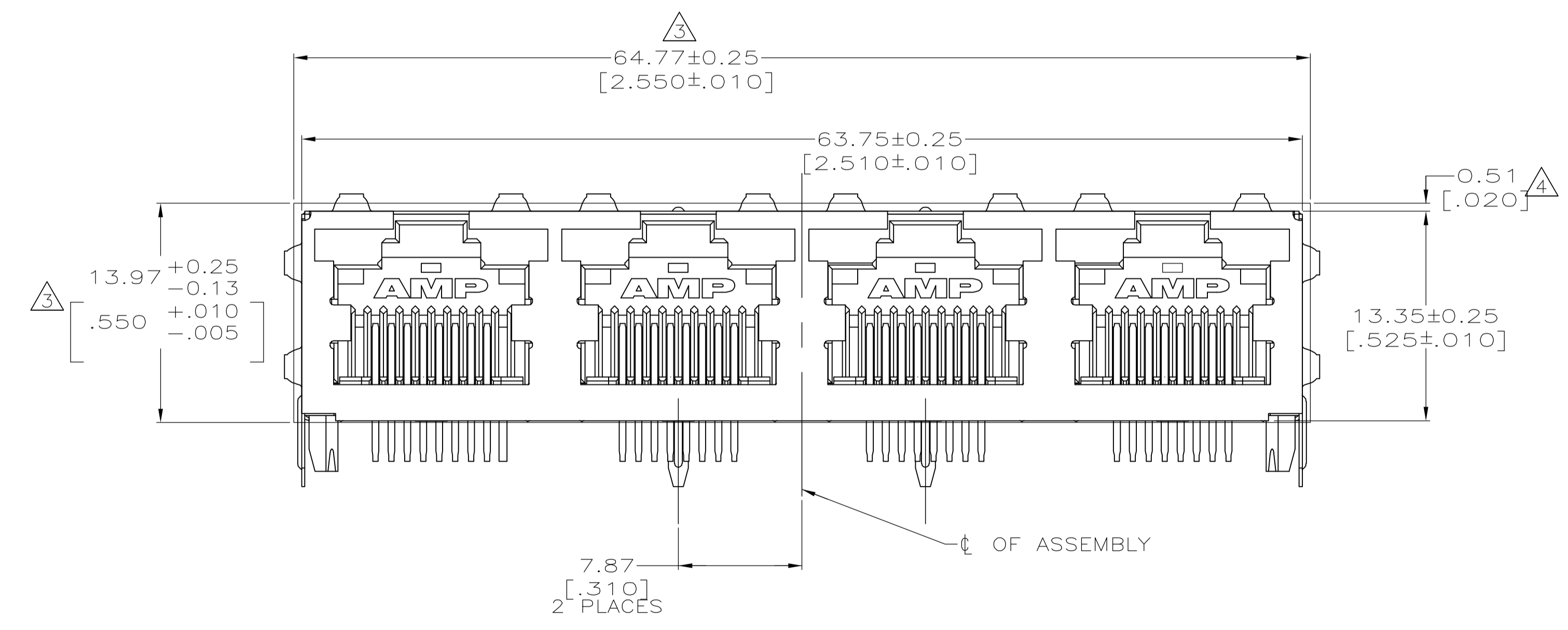
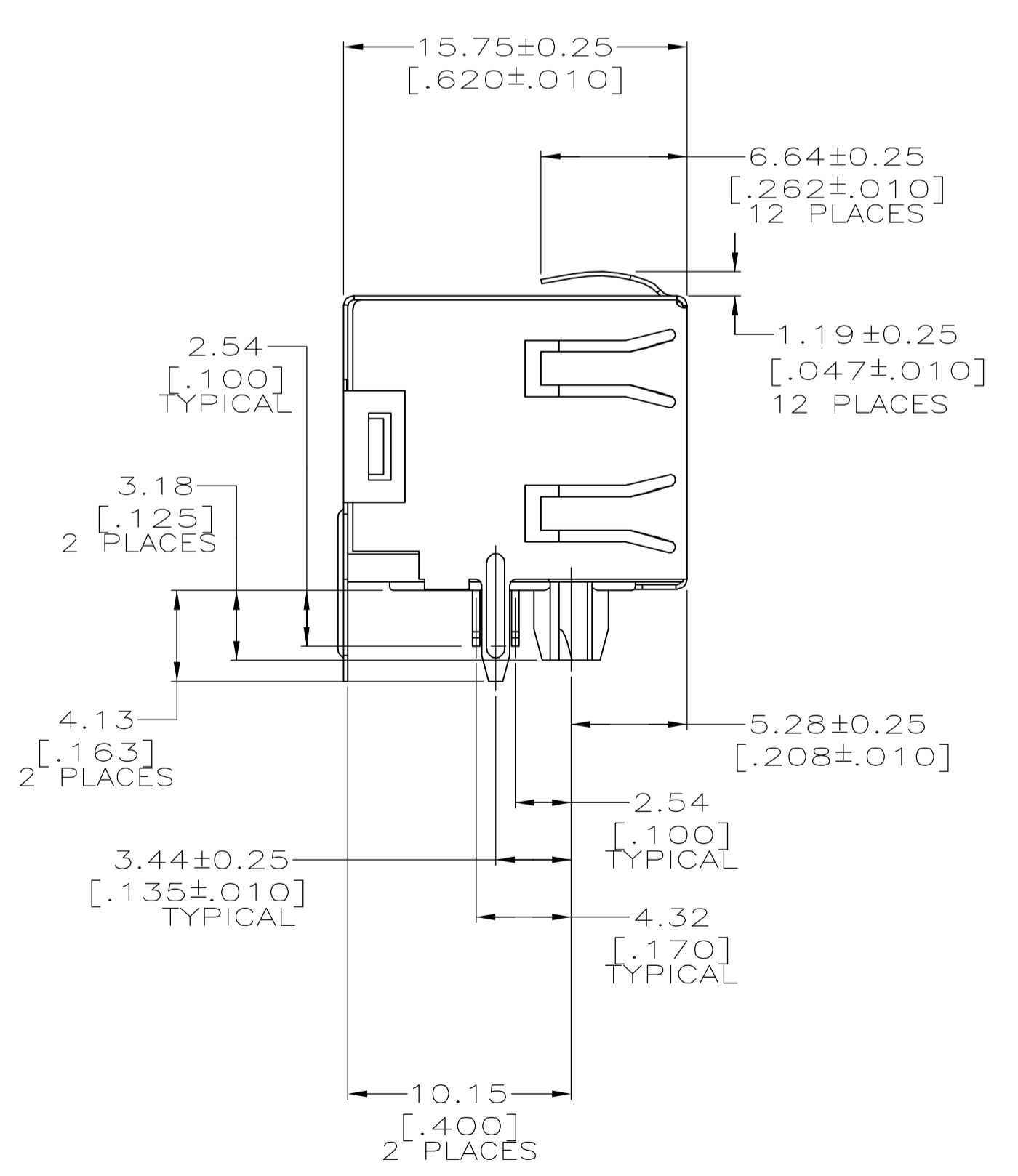


LOC		DIST		REVISIONS			
AA	22	P	L/R	DESCRIPTION	DATE	DWN	APVD
C				REV PER ECO-07-004331	28FEB07	TK	JW



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



- △ MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN LEAD POST DIPPED ON PCB GROUND TABS.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

406544-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. WOOTEN 22SEP97		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK T. SPRINKLE 29SEP97		APVD M. DERSTINE 060CT97	NAME INVERTED MOD JACK ASSEMBLY, 1x4, SHIELDED, PANEL GROUND
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-1163-4		APPLICATION SPEC 114-2154	
0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± -		SIZE A1		CAGE CODE 00779	
MATERIAL △		DRAWING NO 406544		RESTRICTED TO -	
FINISH -		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV C	